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United States Patent [19]
Klinker

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[45] **Date of Patent: ** *Aug. 31, 1999**

[54] **PROCESSOR PACKAGE COVER PLATE FOR AN INTEGRATED CIRCUIT PROCESSOR PACKAGE CHIPSET**

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[73] Assignee: **Intel Corporation**, Santa Clara, Calif.

[*] Notice: This patent is subject to a terminal disclaimer.

[**] Term: **14 Years**

[21] Appl. No.: **29/081,114**

[22] Filed: **Dec. 22, 1997**

[51] **LOC (6) Cl.** **14-02**

[52] **U.S. Cl.** **D14/114**

[58] **Field of Search** D14/114, 121; D13/156; D8/353; 242/348, 348.4, 341, 342, 343, 344-5, 345.1, 346, 345.3, 346.2; 273/148 R, 148 B; D21/324-33; 257/678-9; 361/737, 752

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[57] **CLAIM**

The ornamental design for a processor package cover plate for an integrated circuit processor package chipset, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a cover plate on a processor package including an indented area on a surface of the cover plate.

FIG. 2 is a front view thereof.

FIG. 3 is a top view thereof.

FIG. 4 is a back view thereof.

FIG. 5 is a right side view thereof.

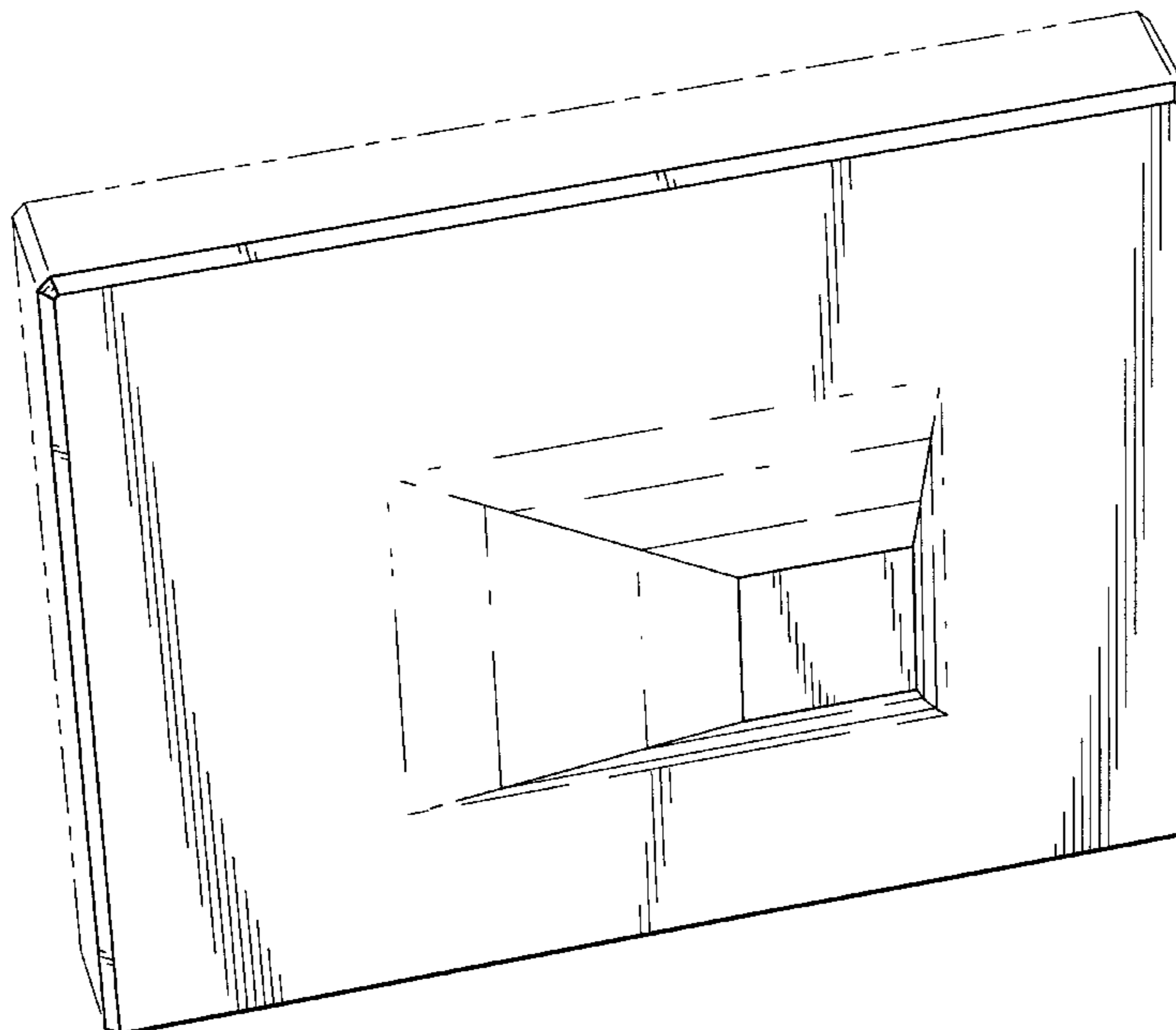
FIG. 6 is a left side view thereof.

FIG. 7 is a bottom view thereof; and,

FIG. 8 is a cross-sectional view thereof, taken on line 8—8 of FIG. 2.

The broken line drawing in FIGS. 1, 3, and 5-8 of the processor package is for illustrative purposes only and forms no part of the claimed design.

1 Claim, 4 Drawing Sheets



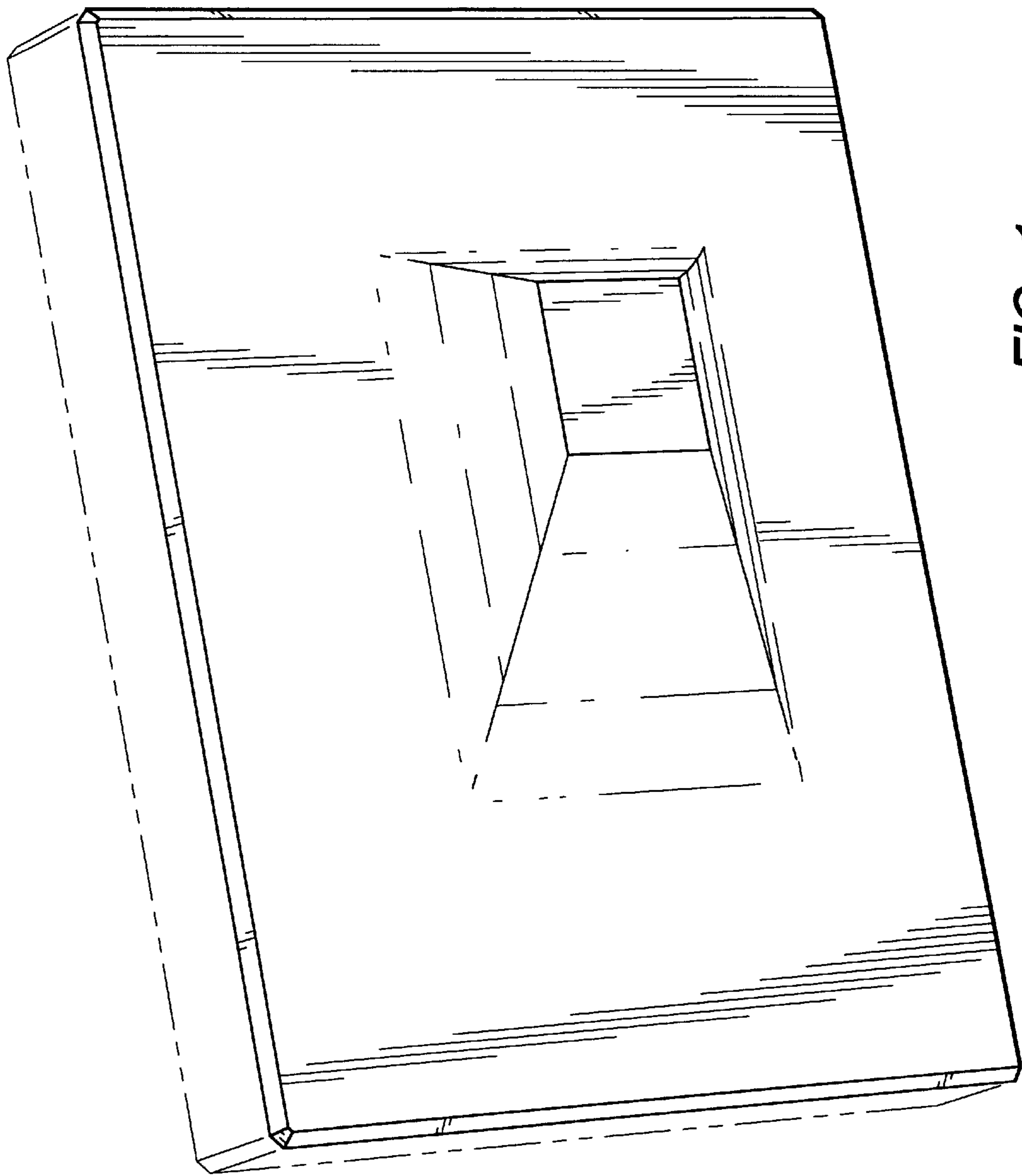


FIG. 1

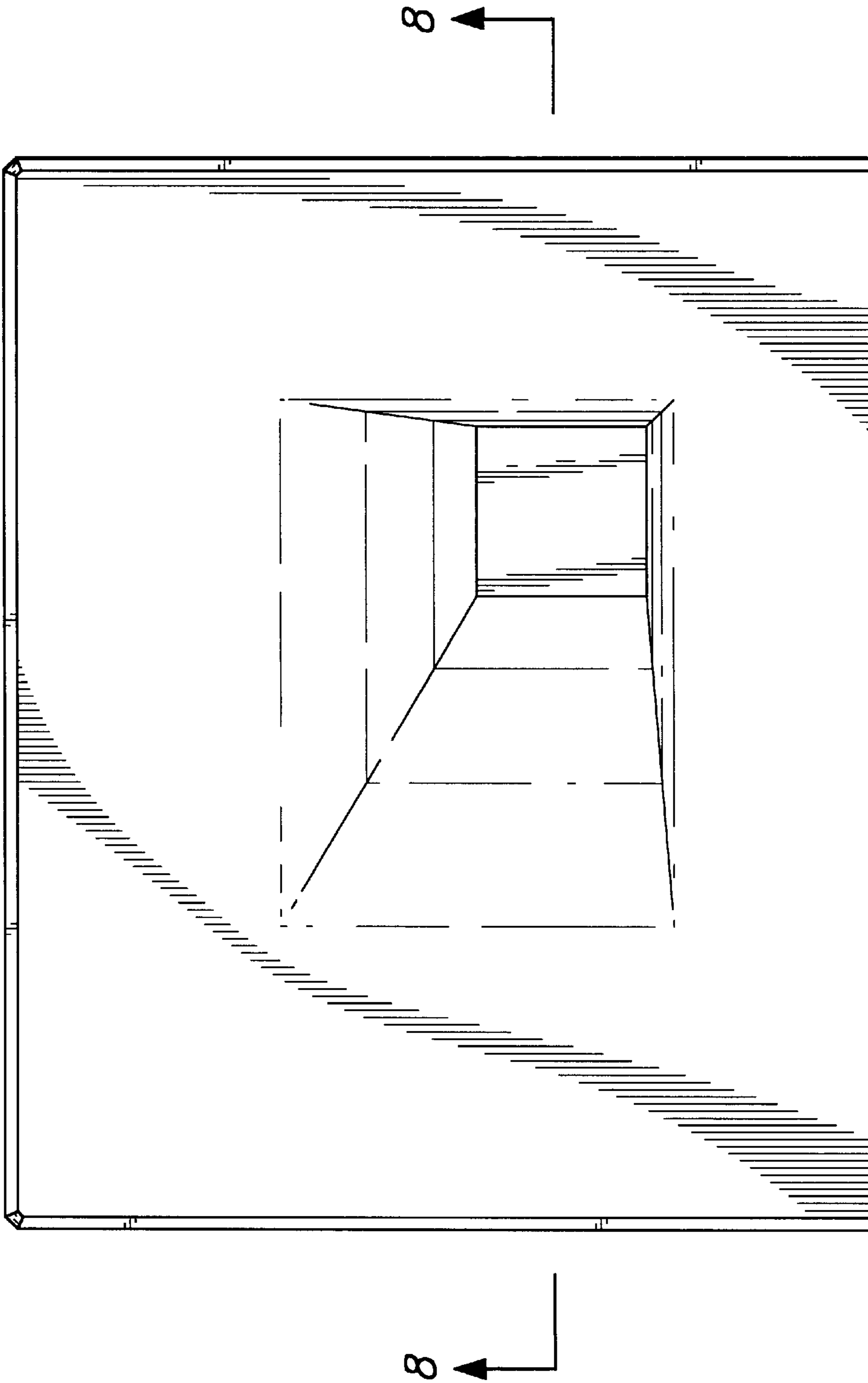


FIG. 2

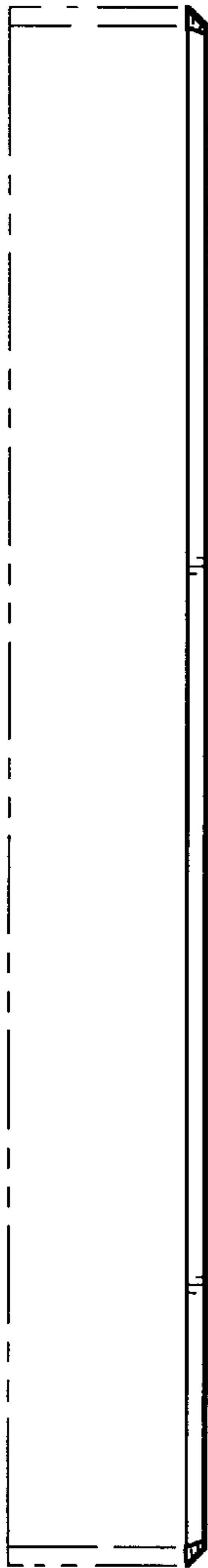


FIG. 3

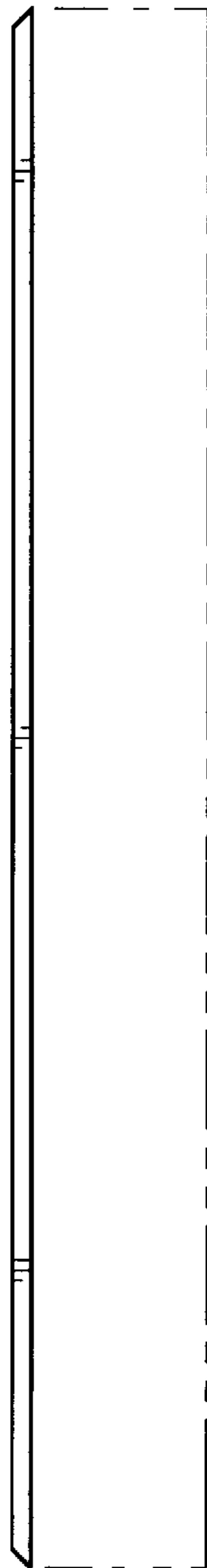


FIG. 7

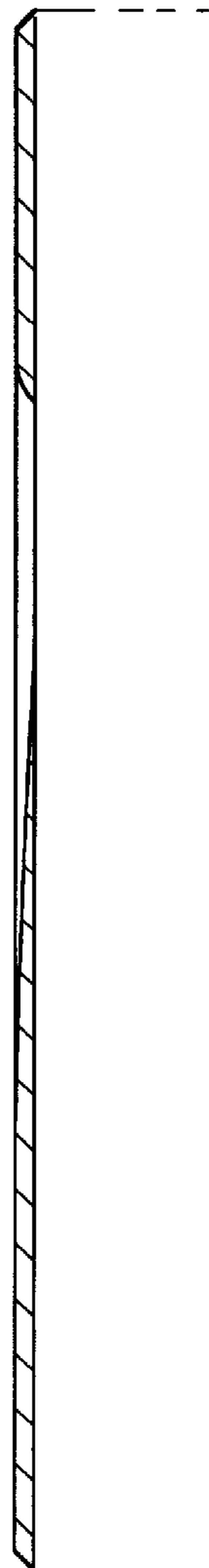


FIG. 8

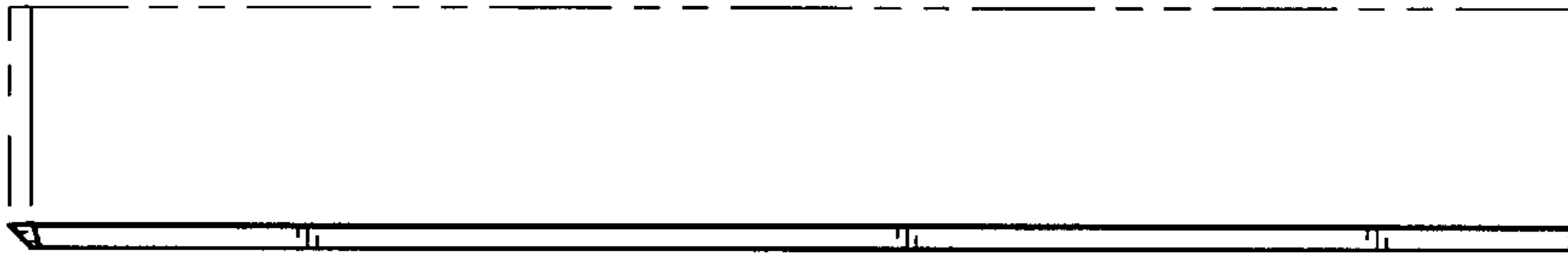


FIG. 5

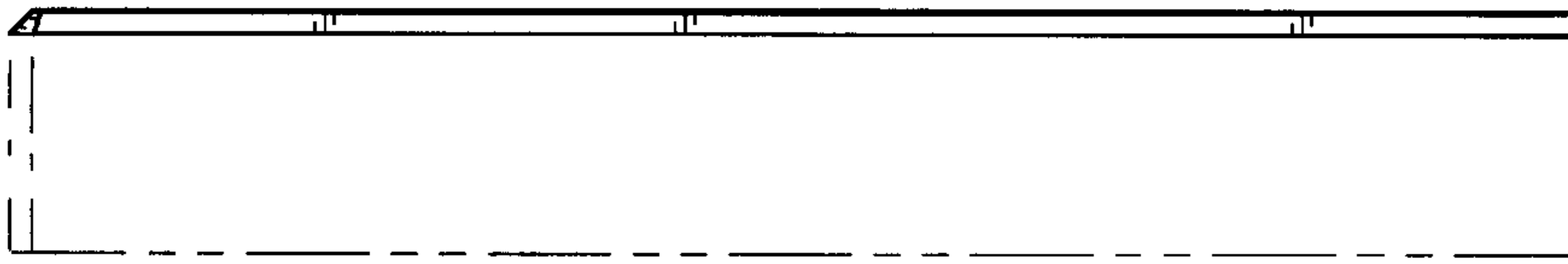


FIG. 6

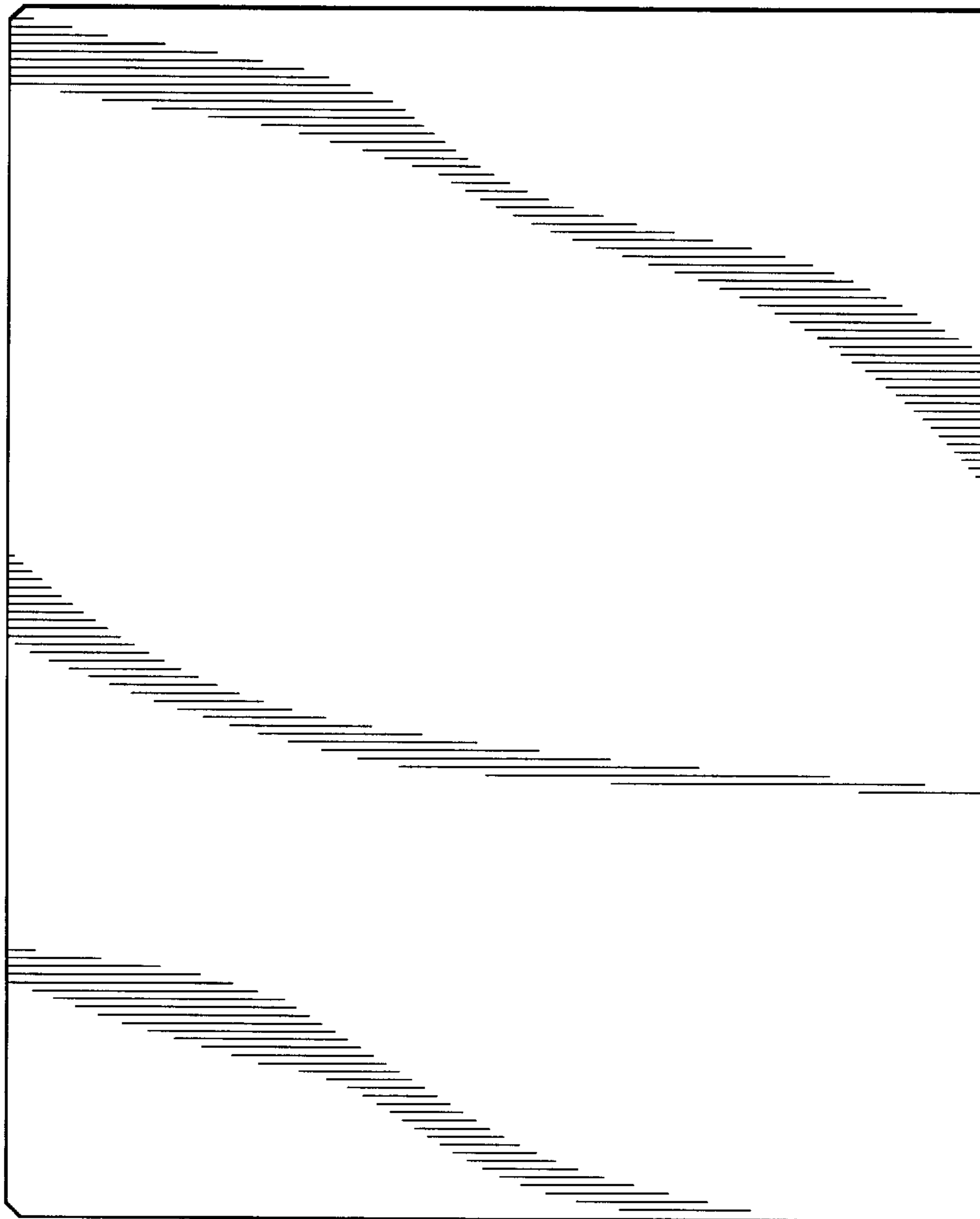


FIG. 4